



PK646 (v1.0) April 12, 2014

100% Material Declaration Data Sheet for Artix®-7 RB676 Package

Average Weight: 7.5003 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.237267	3.163
	Silicon	7440-21-3	100.00	Basis	0.237267	
Solder Bump					0.011261	0.150
	Tin	7440-31-5	63.00	Basis	0.007094	
	Lead	7439-92-1	37.00	Basis	0.004167	
Underfill					0.027300	0.364
	Bisphenol F/ Epichlorohydrin	9003-36-5	20.00	Basis	0.005460	
	Phenolic Resin	Trade Secret	15.00	Basis	0.004095	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.001365	
	Amine type accelerator	Trade Secret	5.00	Basis	0.001365	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.014060	
	Carbon Black	1333-86-4	1.00	Basis	0.000273	
	Additives	Trade Secret	2.50	Additive	0.000683	
Heat Sink					4.615000	61.531
	Copper	7440-50-8	97.94	Main Material	4.519931	
	Nickel	8049-31-8	2.06	Main Material	0.095069	
Heat Sink Adhesive					0.057200	0.763
	Aluminium Oxide Al ₂ O ₃	1344-28-1	70.00	Main Material	0.040040	
	Dimethyl siloxane, dimethylvinyl- terminated	68083-19-2	30.00	Main Material	0.017160	
Solder Ball					0.643415	8.578
	Tin	7440-31-5	63.00	Main Material	0.405351	
	Lead	7439-92-1	37.00	Main Material	0.238064	
Substrate					1.908894	25.451
	Copper	7440-50-8	37.00		0.706291	
	Tin	7440-31-5	1.67		0.031879	
	Lead	7439-92-1	0.33		0.006299	
	Silver	7440-22-4	0.03		0.000573	
	BT Core	Trade Secret	49.35		0.942039	
	ABF	Trade Secret	11.49		0.219332	
	Solder Mask	Trade Secret	0.13		0.002482	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/12/2014	1.0	Xilinx Initial Release

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